

IN THE SPECIFICATION:

Please amend the paragraph beginning at page 5, line 27 as follows:

As shown in Fig. 3, each electrical connection pad 17 on the integrated circuit device 3 has an external surface 39 generally parallel with the device and comprises at least one, and probably more than one, socket 35. Each socket comprises at least two resilient members in the form of adjacent spring fingers, designated 43a and 43b, that cooperate to form the socket. In the illustrated embodiment, each socket 35 comprises two spring fingers 43a, 43b with one of the fingers 43a being generally C-shaped and the adjacent spring finger 43b being a mirror image of the C-shaped finger. Each spring finger 43a, 43b is a curved conductive metal strip that protrudes from the flat external surface 39 of the pad 17. Spring finger 43a has an inturned free end portion 47a that converges near the opposed free end portion 47b of the adjacent spring member 43b. Spring fingers 43a, 43b have respective pad connection portions 49a, 49b attached to the connection surface 39 of the pad 17. In the illustrated embodiment, each pad connection portion 49a, 49b extends generally parallel to the connection surface 39 of the pad 17 and is attached in face-to-face contact with the connection surface. It will be understood that the resilient spring fingers 43a, 43b may have other shapes and configurations without departing from the scope of this invention. In one embodiment, each spring finger 43a, 43b is fabricated on the electrical connection pad 17 and is made from a "stress-engineered" metal or metal alloy (e.g., molybdenum (Mo), molybdenum chromide (MoCr), or nickel zirconium (NiZr)) as disclosed in United States Patent No. 6,560,861, incorporated by reference herein for all purposes. It will be understood that the spring fingers 43a, 43b can be manufactured and attached to the electrical connection pads in

accordance with existing circuit fabrication methods such as any of the typical methods disclosed in the '861 patent or any other conventional micro-circuit fabrication method.